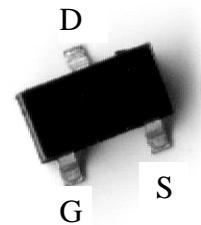


**20V N-CHANNEL Enhancement Mode MOSFET****Outline**

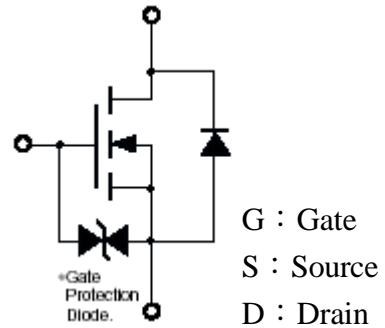
SOT-523

**Features:**

- Simple drive requirement
- Small package outline
- Pb-free lead plating and halogen-free package

**Symbol**

KW2120EUY



BVDSS	20V
ID	560mA
RDS(on)@VGS=4.5V, ID=600mA	320mΩ (typ)
RDS(on)@VGS=2.5V, ID=400mA	510mΩ (typ)
RDS(on)@VGS=1.8V, ID=350mA	980mΩ (typ)

**Ordering Information**

Device	Package	Shipping
KW2120EUY	SOT-523 (Pb-free lead plating package)	3000 pcs / tape & reel



## Absolute Maximum Ratings ( $T_a=25^\circ C$ )

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current @ $T_A=25^\circ C$ , $V_{GS}=4.5V$ (Note 3)	$I_D$	560	mA
Continuous Drain Current @ $T_A=85^\circ C$ , $V_{GS}=4.5V$ (Note 3)		400	
Pulsed Drain Current (Notes 1, 2)	$I_{DM}$	2.5	A
Maximum Power Dissipation (Note 3)	$P_D$	150	mW
		80	
ESD susceptibility		2000 (Note 4)	V
Operating Junction and Storage Temperature	$T_j, T_{stg}$	-55~+150	°C

Note : 1. Pulse width limited by maximum junction temperature.

2. Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

3. Surface mounted on FR-4 board.

3. Human body model,  $1.5k\Omega$  in series with  $100pF$

## Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient(PCB mounted)	$R_{th,ja}$	833	°C/W

## Electrical Characteristics ( $T_j=25^\circ C$ , unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
$BV_{DSS}$	20	-	-	V	$V_{GS}=0, I_D=250\mu A$
$\Delta BV_{DSS}/\Delta T_j$	-	0.02	-	V/°C	Reference to $25^\circ C$ , $I_D=1mA$
$V_{GS(th)}$	0.5	0.92	1.2	V	$V_{DS}=V_{GS}, I_D=250\mu A$
$I_{GSS}$	-	-	$\pm 10$	$\mu A$	$V_{GS}=\pm 8V, V_{DS}=0$
$I_{DSS}$	-	-	1		$V_{DS}=20V, V_{GS}=0$
	-	-	10		$V_{DS}=16V, V_{GS}=0$ ( $T_j=70^\circ C$ )
$*R_{DS(ON)}$	-	320	450	$m \swarrow$	$V_{GS}=4.5V, I_D=600mA$
	-	510	700		$V_{GS}=2.5V, I_D=500mA$
	-	980	1200		$V_{GS}=1.8V, I_D=350mA$
$*G_{FS}$	-	1	-	S	$V_{DS}=10V, I_D=400mA$
<b>Dynamic</b>					
$C_{iss}$	-	60	-	pF	$V_{DS}=10V, V_{GS}=0, f=1MHz$
$C_{oss}$	-	14	-		
$C_{rss}$	-	9	-		

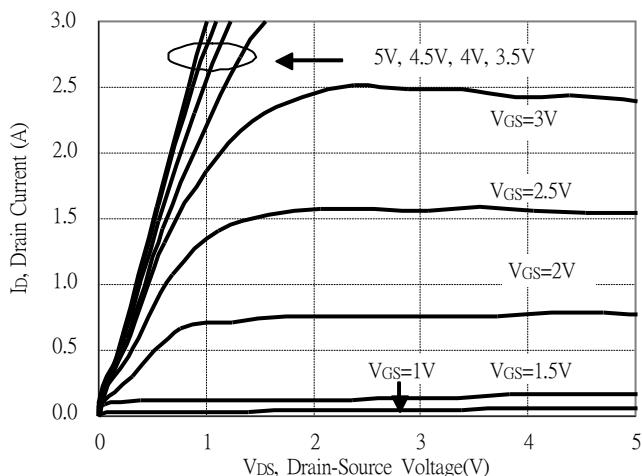


$t_{d(ON)}$	-	5	-	ns	$V_{DS}=10V, I_D=200mA, V_{GS}=4.5V$ $R_G=10\Omega$
$t_r$	-	5	-		
$t_{d(OFF)}$	-	24	-		
$t_f$	-	18	-		
$Q_g$	-	0.76	-	nC	$V_{DS}=10V, I_D=250mA, V_{GS}=4.5V$
$Q_{gs}$	-	0.074	-		
$Q_{gd}$	-	0.27	-		
<b>Source-Drain Diode</b>					
* $V_{SD}$	-	0.8	1.2	V	$V_{GS}=0V, I_s=150mA$

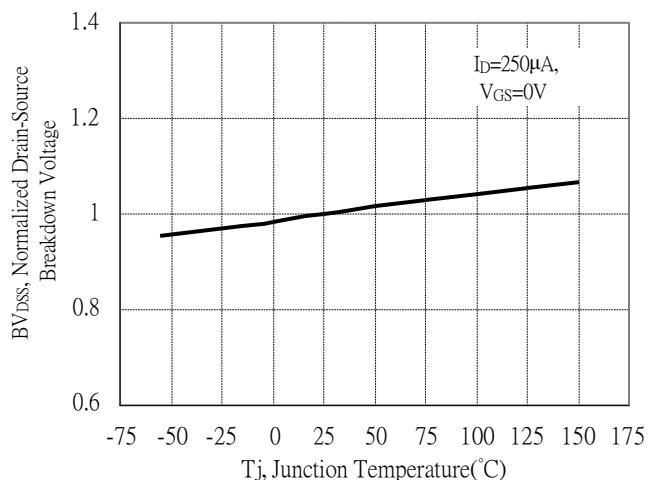
\*Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$

## Typical Characteristics

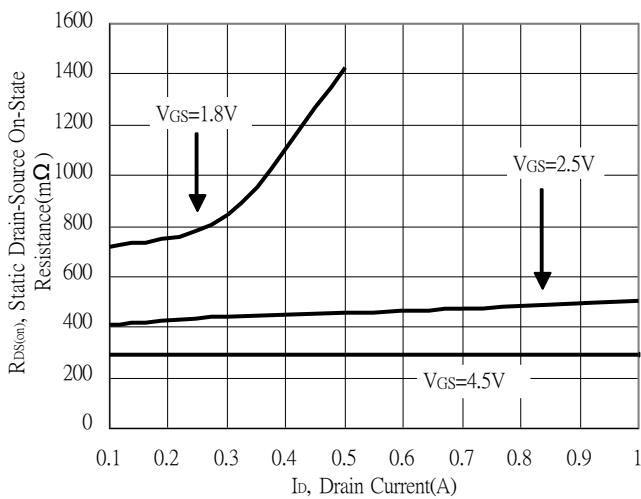
Typical Output Characteristics



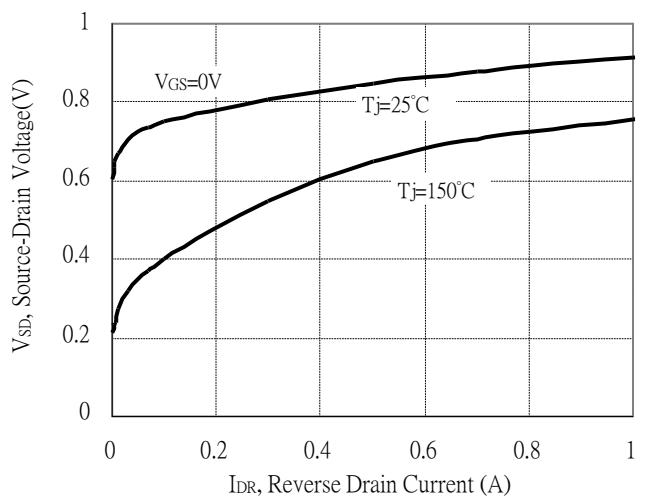
Breakdown Voltage vs Ambient Temperature



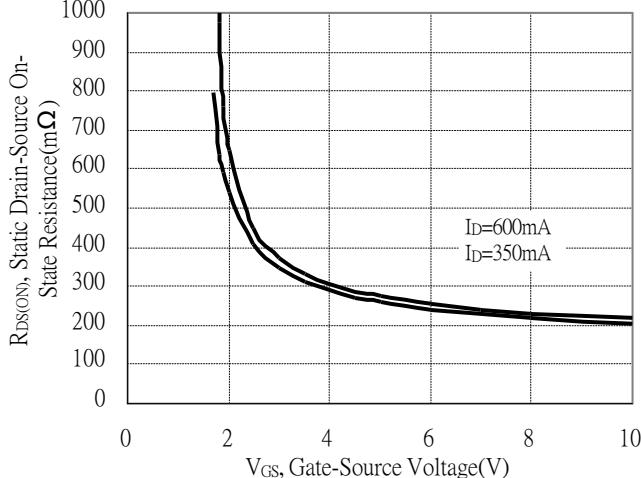
Static Drain-Source On-State resistance vs Drain Current



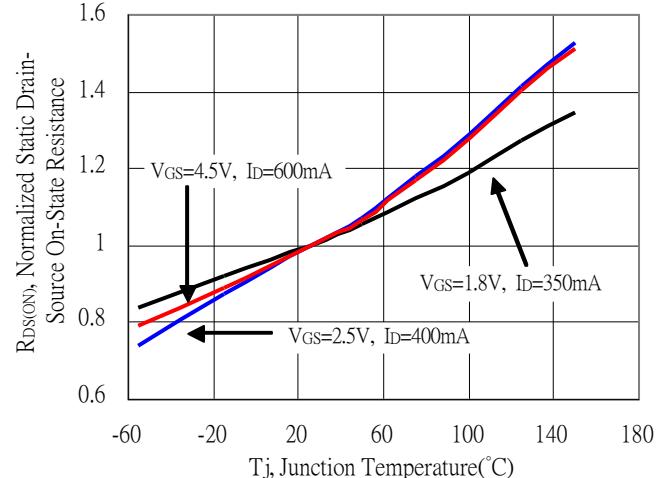
Reverse Drain Current vs Source-Drain Voltage



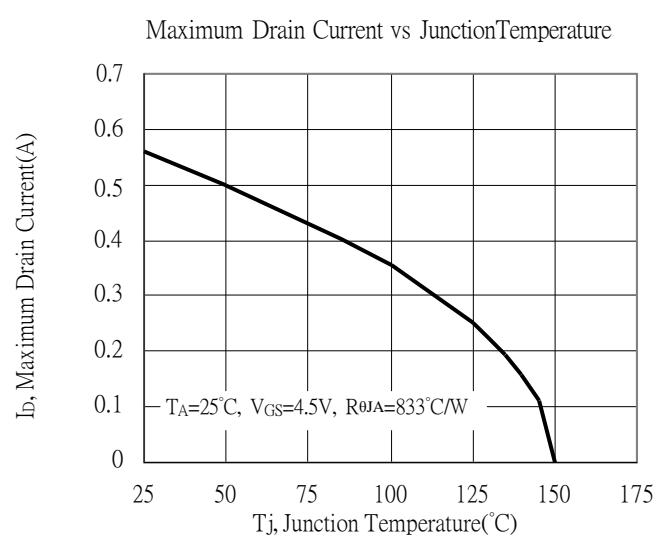
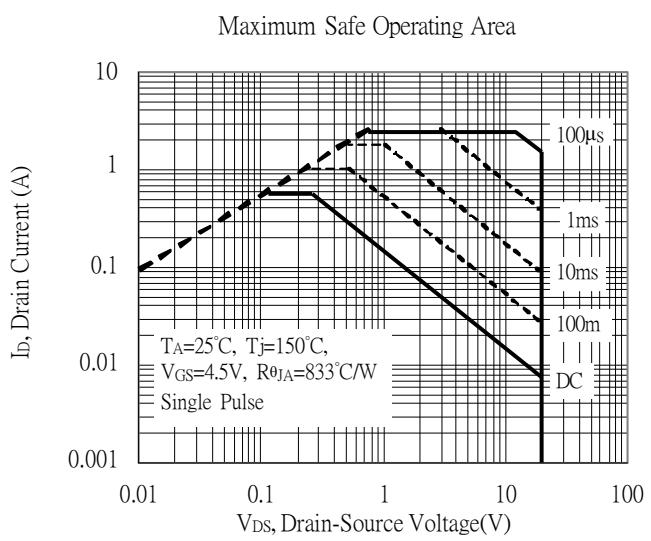
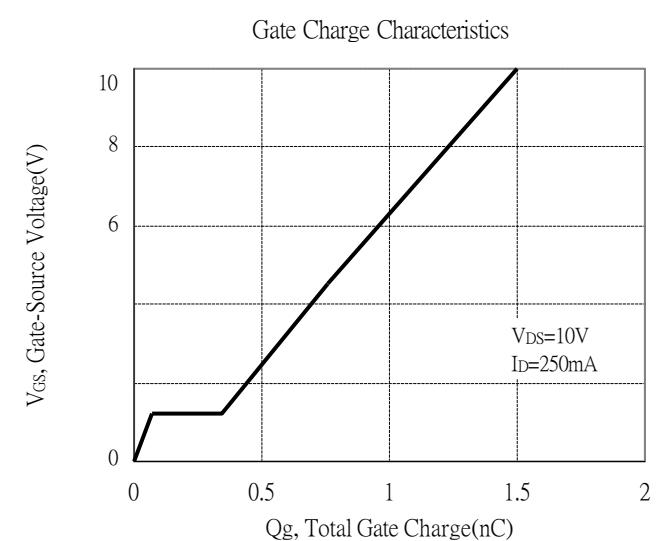
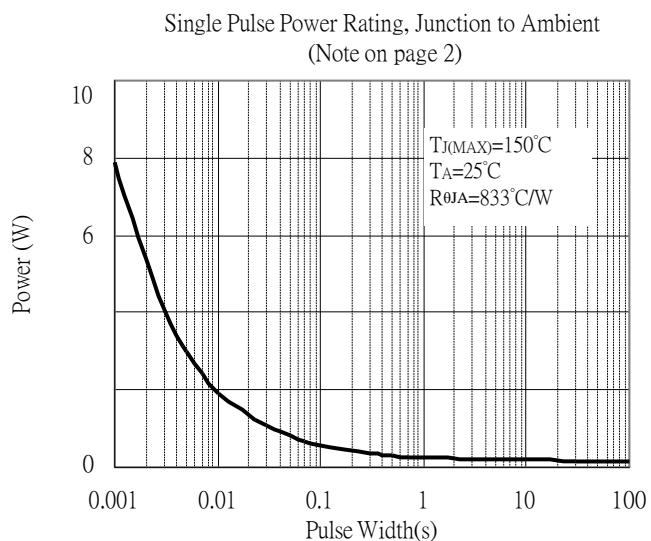
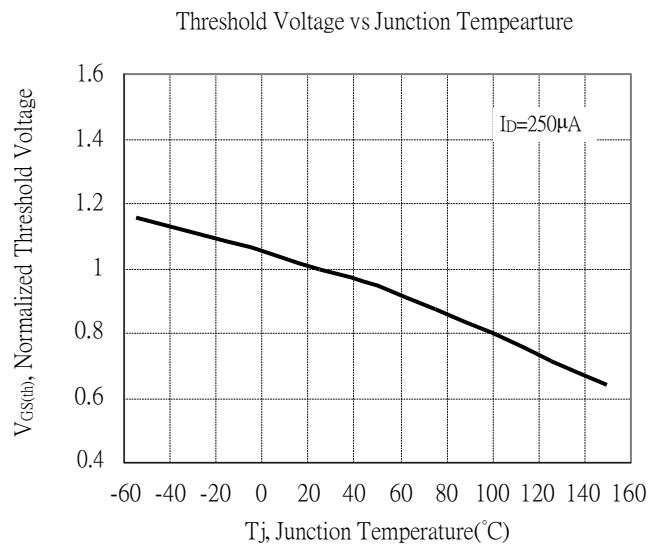
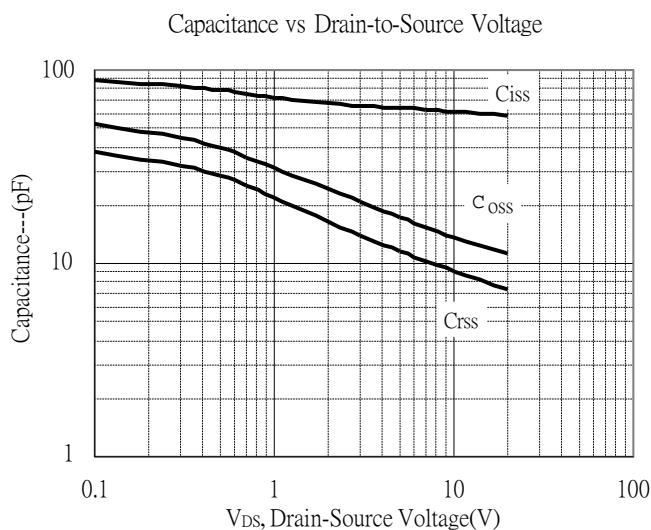
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

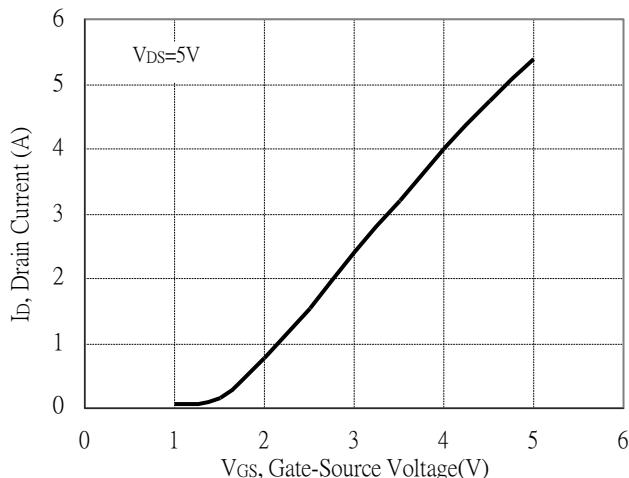


## Typical Characteristics(Cont.)

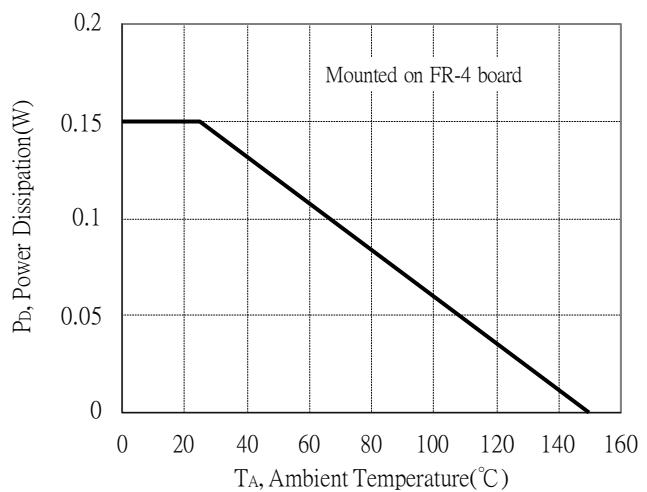


## Typical Characteristics(Cont.)

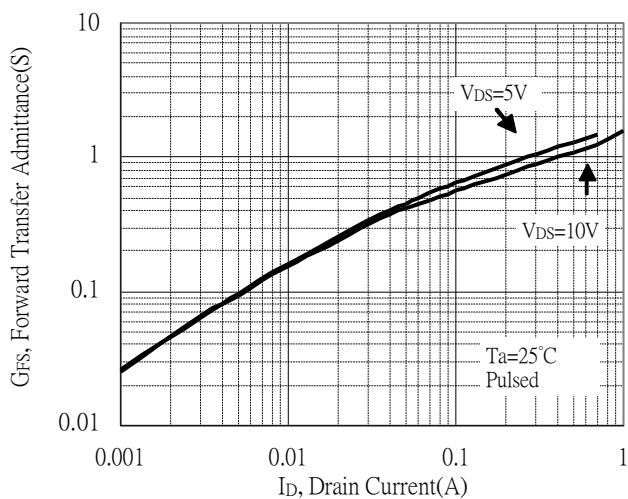
Typical Transfer Characteristics



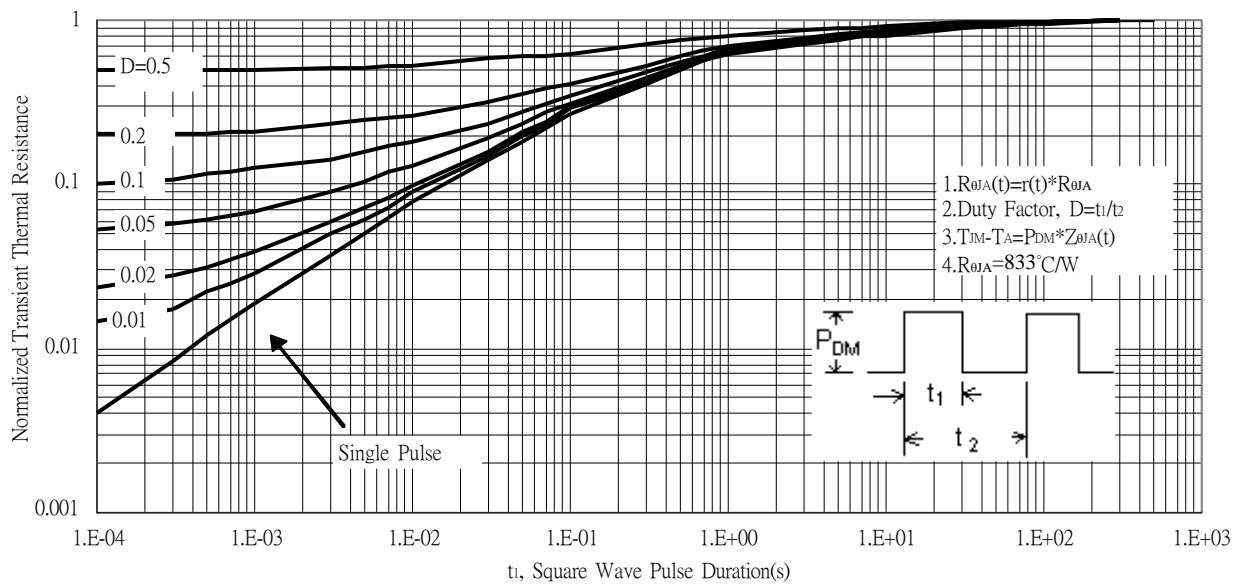
Power Derating Curve



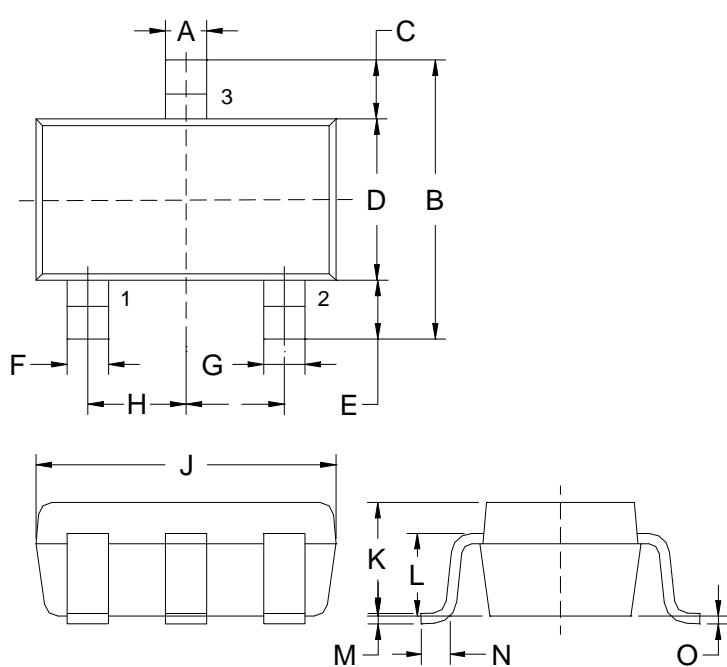
Forward Transfer Admittance vs Drain Current



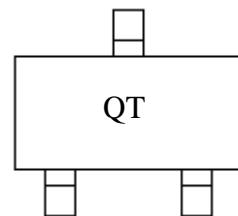
Transient Thermal Response Curves



## SOT-523 Dimension



Marking:



3-Lead SOT-523 Plastic  
Surface Mounted Package  
Code: C3

Style: Pin 1.Gate 2.Source 3.Drain

\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0079	0.0157	0.20	0.40	I	*0.0197	-	*0.50	-
B	0.0591	0.0669	1.50	1.70	J	0.0610	0.0650	1.55	1.65
C	0.0118	0.0197	0.30	0.50	K	0.0276	0.0315	0.70	0.80
D	0.0295	0.0335	0.75	0.85	L	0.0224	0.0248	0.57	0.63
E	0.0118	0.0197	0.30	0.50	M	0.0020	0.0059	0.05	0.15
F	0.0039	0.0118	0.10	0.30	N	0.0039	0.0118	0.10	0.30
G	0.0039	0.0118	0.10	0.30	O	0	0.0031	0	0.08
H	*0.0197	-	*0.50	-					